ABBOCIATION CONNECTING ELECTRONICE INDUSTRIES® INCLUSTRIES®	burn, Illinois. All rights reserved	under both This do level pa	cument is a dec rts, the declarat	claration tion enc	of the substances ompasses all lowe	within the manufacture or level materials for wh	er listed it hich the m	em. Note: if tl anufacturer h	he item is an as as engineering i	sembly with lower esponsibility.	
IPC Web Site for Information on http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information											
Company name*	any name* Company unique ID			Unique ID Authority			Response Date*				
onsemi								2023-06-08			
Contact Name	Title - Contact		Phone - C	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Representative		Phone - R	Phone - Representative*			Email - Representative*				
Product-Env-Stewards	act-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iter	n Number Mfr Item Name	Mfr Item Name		Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
L78MS DLM-E		UT Voltage Regulator	2023-06-0	08	РНМ		1	300.0	mg	Each	
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak	Peak Process B		Body Temperature Max Time at Peak		ure Number	of Reflow Cyc	les	
contains Bi	contains Bi CU Alloy 3		260		С	30	second	is 3			
Comments											
ATTENTION: MSL 3 Rated item requires Bake and l	Dry Pack (after electrical test)										
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.62	mg	Supplier	Silicon (Si)	7440-21-3		2.62	mg
Die Attach	0.76	mg	Supplier	Silver (Ag)	7440-22-4		0.0228	mg
			А	Lead (Pb)	7439-92-1	7a	0.7144	mg
			Supplier	Tin (Sn)	7440-31-5		0.0152	mg
			Supplier	Copper (Cu)	7440-50-8		0.0076	mg
Lead Frame	790.42	mg	Supplier	Tin (Sn)	7440-31-5		0.8695	mg
			Supplier	Copper (Cu)	7440-50-8		789.5505	mg
Mold Compound-Black	499.42	mg		Brominated epoxy resin	proprietary data		9.9884	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		0.9988	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		15.482	mg
			Supplier	Carbon Black (C)	1333-86-4		1.4983	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		370.5696	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		99.884	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.9988	mg
Plating	6.65	mg	В	Bismuth (Bi)	7440-69-9		0.0399	mg
			Supplier	Tin (Sn)	7440-31-5		6.6101	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg